

Surface Mount Schottky Power Rectifier Plastic SOD-123 Package

MBR140ESF, NRVB140ESF

This device uses the Schottky Barrier principle with a large area metal-to-silicon power diode. Ideally suited for low voltage, high frequency rectification or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package also provides an easy to work with alternative to leadless 34 package style. Because of its small size, it is ideal for use in portable and battery powered products such as cellular and cordless phones, chargers, notebook computers, printers, PDAs and PCMCIA cards. Typical applications are AC-DC and DC-DC converters, reverse battery protection, and “Oring” of multiple supply voltages and any other application where performance and size are critical.

Features

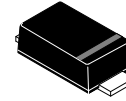
- Guardring for Stress Protection
- Low Reverse Leakage
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- ESD Rating:
 - ♦ Human Body Model = 3B
 - ♦ Machine Model = M4
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant*

Mechanical Characteristics

- Device Marking: E4F
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

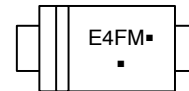
*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES 40 VOLTS



SOD-123FL
CASE 498

MARKING DIAGRAM



E4F = Specific Device Code
M = Date Code
■ = Pb-Free Package)

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
MBR140ESFT1G	SOD-123FL (Pb-Free)	3,000 / Tape & Reel **
MBR140ESFT3G	SOD-123FL (Pb-Free)	10,000 / Tape & Reel ***
NRVB140ESFT1G	SOD-123FL (Pb-Free)	3,000 / Tape & Reel **
NRVB140ESFT3G	SOD-123FL (Pb-Free)	10,000 / Tape & Reel ***

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

** 8 mm Tape, 7" Reel

*** 8 mm Tape, 13" Reel

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	40	V
Average Rectified Forward Current	I_O	1.0	A
Peak Repetitive Forward Current	I_{FRM}	2.0	A
Non-Repetitive Peak Surge Current (Non-Repetitive peak surge current, halfwave, single phase, 60 Hz)	I_{FSM}	30	A
Storage Temperature	T_{stg}	-55 to 175	°C
Operating Junction Temperature	T_J	-55 to 175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1)	R_{tjl}	26	°C/W
Thermal Resistance, Junction-to-Lead (Note 2)	R_{tjl}	21	
Thermal Resistance, Junction-to-Ambient (Note 1)	R_{tja}	325	
Thermal Resistance, Junction-to-Ambient (Note 2)	R_{tja}	82	

1. Mounted with minimum recommended pad size, PC Board FR4.
2. Mounted with 1 in. copper pad (Cu area 700 mm²).

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ($I_F = 1.0$ A)	V_F	$T_J = 25^\circ\text{C}$ 0.56	V
Maximum Instantaneous Reverse Current (Note 3) ($V_R = 40$ V)	I_R	$T_J = 25^\circ\text{C}$ 30	μA

3. Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS

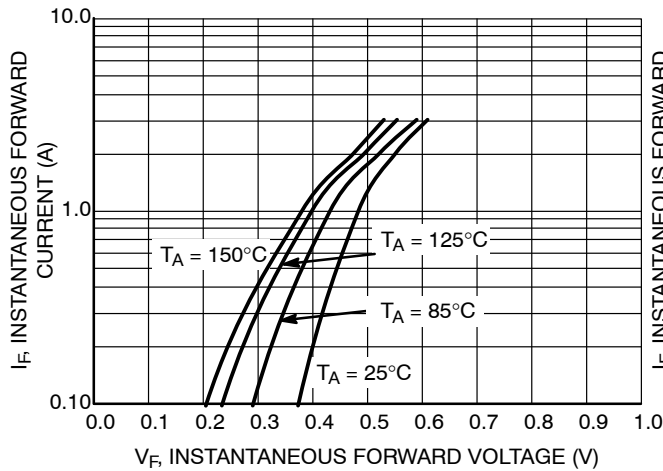


Figure 1. Typical Instantaneous Forward Characteristics

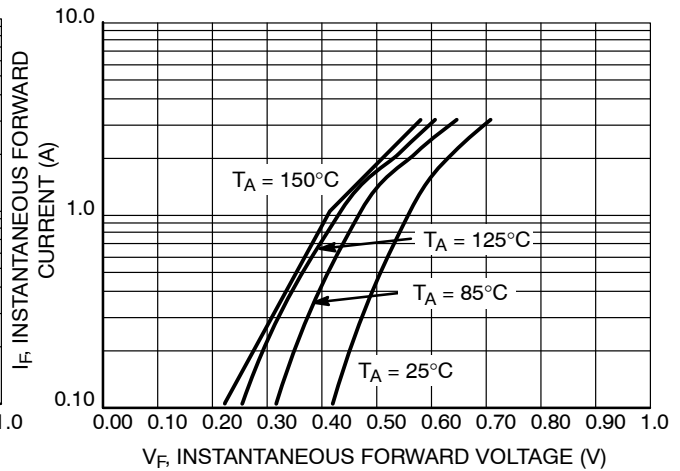


Figure 2. Maximum Instantaneous Forward Characteristics

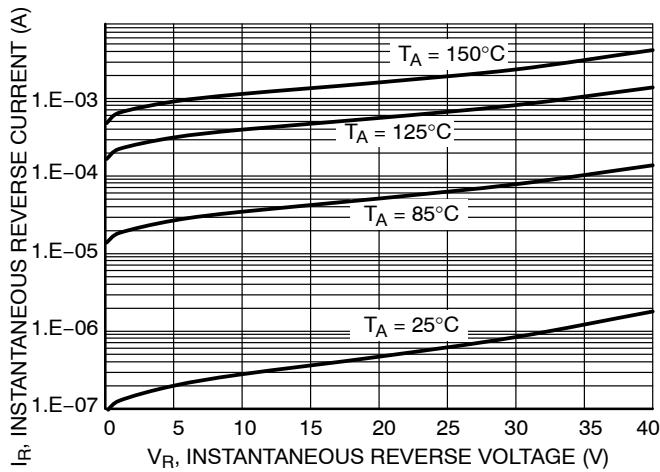


Figure 3. Typical Reverse Characteristics

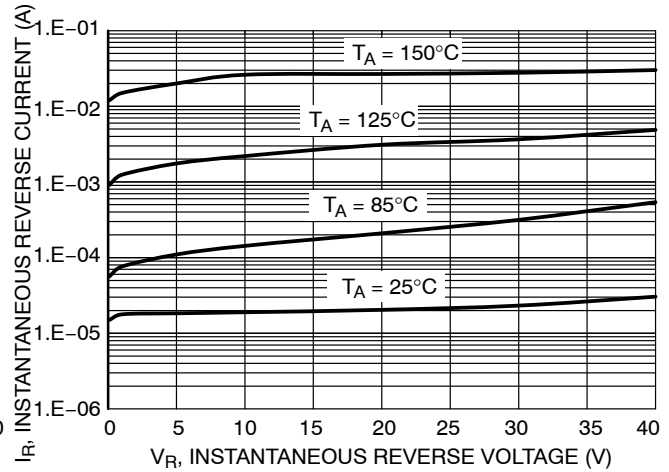


Figure 4. Maximum Reverse Characteristics

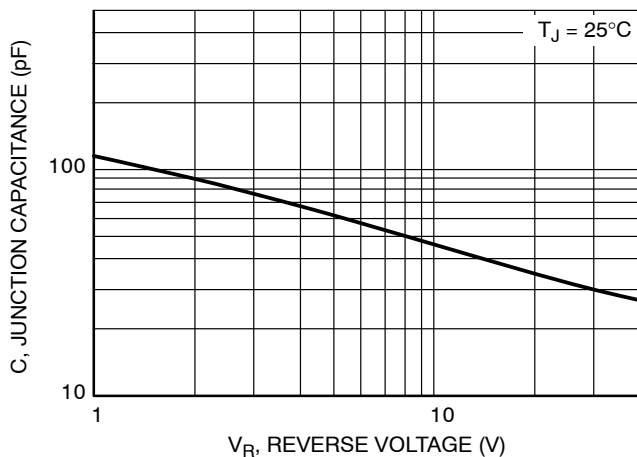


Figure 5. Typical Junction Capacitance

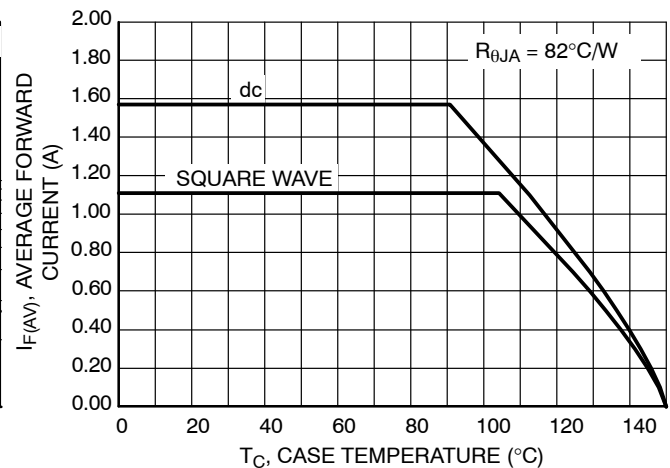


Figure 6. Current Derating, Case

MBR140ESF, NRVB140ESF

TYPICAL CHARACTERISTICS

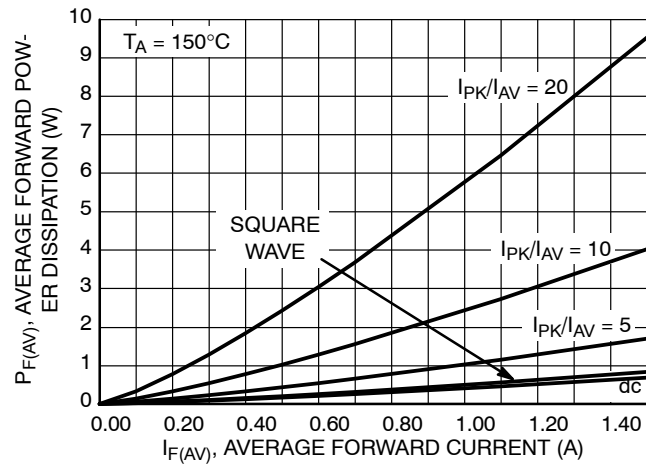


Figure 7. Forward Power Dissipation

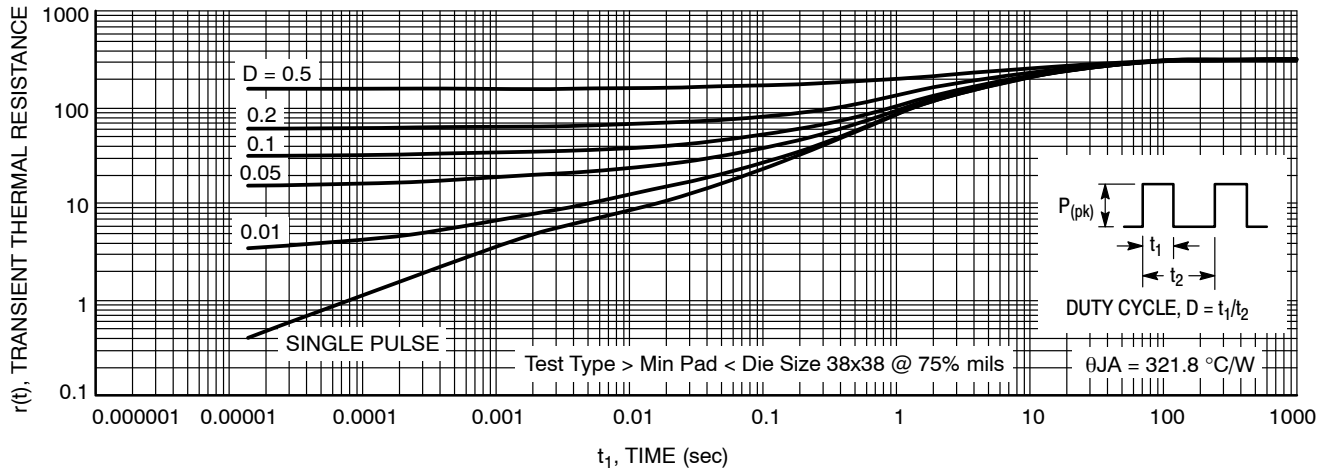
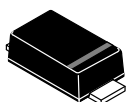


Figure 8. Thermal Response

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

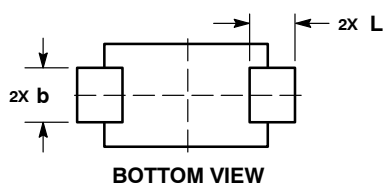
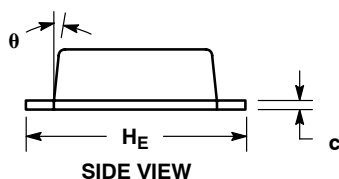
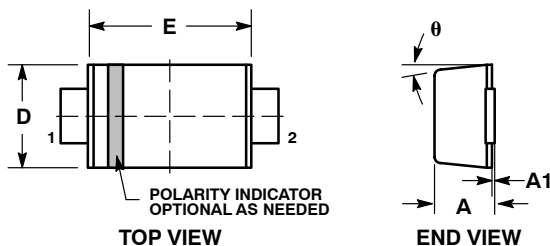
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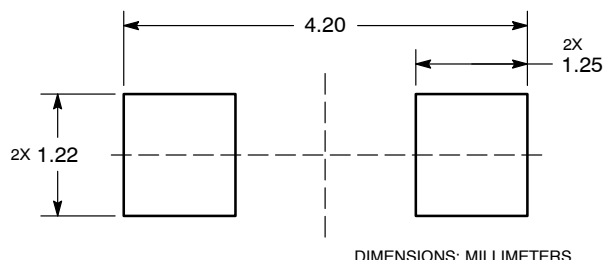
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CASE 498
ISSUE D

DATE 10 MAY 2013



RECOMMENDED SOLDERING FOOTPRINT*

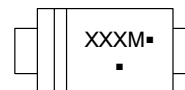


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH.
4. DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	0.95	0.98	0.035	0.037	0.039
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.70	0.90	1.10	0.028	0.035	0.043
c	0.10	0.15	0.20	0.004	0.006	0.008
D	1.50	1.65	1.80	0.059	0.065	0.071
E	2.50	2.70	2.90	0.098	0.106	0.114
L	0.55	0.75	0.95	0.022	0.030	0.037
H_E	3.40	3.60	3.80	0.134	0.142	0.150
θ	0°	—	8°	0°	—	8°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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